ON Semiconductor

# General Announcement

Document# : P7A2AAB
Issue Date : Oct. 24, 2017

| | |
|---|---|
| **Title of Change:** | Update of the General Announcement P774AAB of LOGO replacement of former Fairchild products by ON Semiconductor logo, and Packaging and Labeling change. |
| **Effective Date:** | Packaging and Labeling change: October 30th, 2017.<br>Logo change: Starting October 30th, 2017 (depending on inventories availability) |
| **Contact information:** | Contact your local ON Semiconductor Sales Office |
| **Type of notification:** | ON Semiconductor will consider this change accepted. |
| **Change category:** | ☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☑ Other: Logo, Packaging and Labeling Change |

**Change Sub-Category(s):**

☐ Manufacturing Site Change/Addition
☐ Product specific change
☐ Manufacturing Process Change
☐ Datasheet/Product Doc change
☐ Material Change
☑ Shipping/Packaging/Marking
☑ Other: LOGO change on part marking

**Sites Affected:**

☐ All site(s)
☑ Not applicable
☐ ON Semiconductor site(s)
Select site:
☐ External Foundry/Subcon site(s)
Select site:

**Description and Purpose:**

On Semiconductor acquired Fairchild Semiconductor on September 19th, 2016. As part of the integration, ON Semiconductor is replacing the “Fairchild” logo on the product marking of the former Fairchild product portfolio by the ON Semiconductor logo. For Molded Packaged parts, the “FAIRCHILD” name may be removed over time (part depending). The rest of the marking will not change.

| | Standard Package Parts | Molded Packaged Parts |
|---|---|---|
| Example of current marking with Fairchild logo. |  |  |
| Example of marking after the change, with logo replaced by On Semiconductor logo. |  |  |
| For Molded Packaged parts, the “FAIRCHILD” name may be removed over time (part depending). | n/a |  |

This change will be effective around system integration, which is currently scheduled for Monday, October 30th, 2017. This means that you can start receiving parts with the new logo after October 30th, 2017, depending on inventories availability.

Packaging and Labeling will be changing to the ON Semiconductor standard guidelines. To review the document outlining these guidelines, please visit http://www.onsemi.com/fairchild. The Packaging and Labeling change will be effective on October 30th, 2017.

If customers have questions regarding the system integration please email the questions to Fairchild_questions@onsemi.com.

**List of Affected Part(s):**

This is a General Announcement. General Announcements do not contain a specific list of affected devices. ON Semiconductor uses these announcements when all or no devices are affected.